&TDK Multilayer Ceramic Chip Capacitors CGA3E2X8R1H153K080AA

TDK item description CGA3E2X8R1H153KT****

Applications	Automotive Grade	~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~
Feature	AEC-Q200 AEC-Q200 150°C High Temperature Application	T
Series	CGA3(1608) [EIA 0603]	6
Status	Production (Not Recommended for New Design)	~ B

	Size
Length(L)	1.60mm ±0.10mm
Width(W)	0.80mm ±0.10mm
Thickness(T)	0.80mm ±0.10mm
Terminal Width(B)	0.20mm Min.
Terminal Spacing(G)	0.30mm Min.
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering)
	0.60mm to 0.80mm(Reflow Soldering)

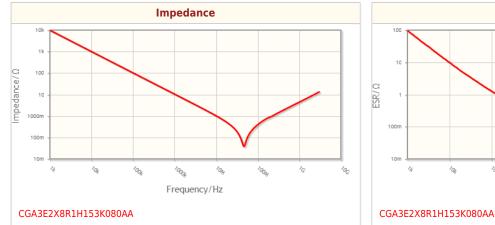
Electrical Characteristics		
Capacitance	15nF ±10%	
Rated Voltage	50VDC	
Temperature Characteristic	X8R(±15%)	
Dissipation Factor (Max.)	3%	
Insulation Resistance (Min.)	10000ΜΩ	

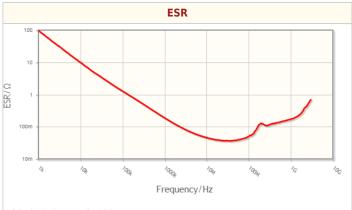
Other	
Coldering Mathed	Wave (Flow)
Soldering Method	Reflow
AEC-Q200	YES
Packing	Punched (Paper)Taping [180mm Reel]
Package Quantity	4000pcs

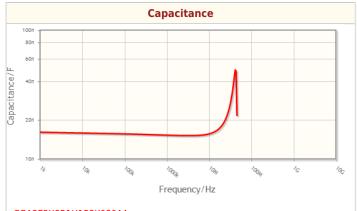
! Images are for reference only and show exemplary products. ! This PDF document was created based on the data listed on the TDK Corporation website.

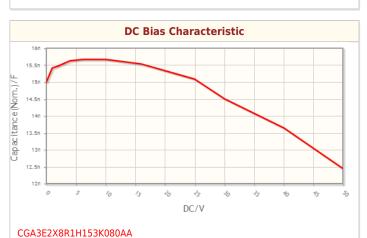
! All specifications are subject to change without notice.

Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)

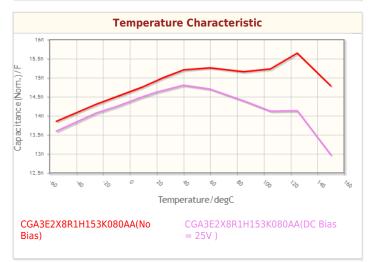


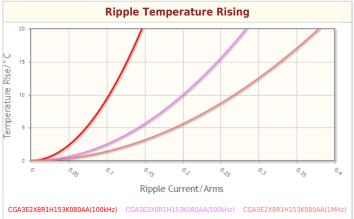












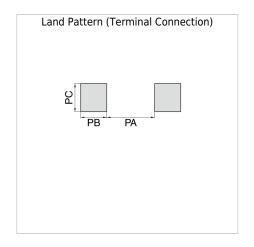
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RoHS Reach Halogen Free Pb Free

Associated Images



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